


MATERIAL DECLARATION SHEET



Material Number	CDDFN6-0504P			
Product Line	Semiconductor Products			
Compliance Date	2008/7/30			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.1223	Silicon	7440-21-3	100.00%	2.46%	2.46%
2	Lead frame	Copper Alloy	2.7306	Copper	7440-50-8	97.45%	54.93%	56.36%
			0.0064	Iron	7439-89-6	0.23%	0.13%	
			0.0008	Phosphorus	7723-14-0	0.03%	0.02%	
			0.0042	Zinc	7440-66-6	0.15%	0.08%	
		Nickel Plating	0.0200	Nickel	7440-02-0	0.71%	0.40%	
		Palladium Plating	0.0200	Palladium	7440-05-3	0.71%	0.40%	
		Gold Plating	0.0200	Gold	7440-57-5	0.71%	0.40%	
3	Epoxy	Polymer	0.0070	Silica crystalline	14808-60-7	42.43%	0.14%	0.33%
			0.0045	Epoxy resin 1	Confidential	27.27%	0.09%	
			0.0025	Epoxy resin 2	Confidential	15.15%	0.05%	
			0.0021	Epoxy resin modifier	Confidential	12.73%	0.04%	
			0.0004	Aromatic amine	Confidential	2.42%	0.01%	
4	Wire	Noble metal	0.03629	Aurum	7440-57-5	99.99%	0.7298%	0.73%

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			0.00001	Others	/	0.01%	0.0002%	
5	Mold Compound	Polymer	0.0599	Epoxy Resin A	Confidential	3.00%	1.20%	40.12%
			0.0299	Epoxy Resin B	Confidential	1.50%	0.60%	
			0.0599	Phenol Resin	Confidential	3.00%	1.20%	
			0.0060	Carbon Black	1333-86-4	0.30%	0.12%	
			1.5964	Silica(Amorphous) A	60676-86-0	80.00%	32.10%	
			0.2435	Silica(Amorphous) B	7631-86-9	12.20%	4.90%	
		Total weight	4.9726 mg					

This Document was updated on: 2015/11/27

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. * 7(a)-Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)